



Material Content Data Sheet



Sales Product Name		SGB10N60A		Issued		29. August 2013		
MA#		MA000534350						
Package		PG-TO263-3-2		Weight*		1461.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.461	0.17	0.17	1684	1684
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		583	
	inorganic material	phosphorus	7723-14-0	0.256	0.02		175	
	non noble metal	copper	7440-50-8	851.691	58.28	58.36	582707	583465
wire	non noble metal	aluminium	7429-90-5	1.374	0.09	0.09	940	940
encapsulation	organic material	carbon black	1333-86-4	8.891	0.61		6083	
	plastics	epoxy resin	-	97.803	6.69		66915	
	inorganic material	silicondioxide	60676-86-0	486.053	33.25	40.55	332546	405544
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6607	6607
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156
solder	noble metal	silver	7440-22-4	0.059	0.00		40	
	non noble metal	tin	7440-31-5	0.047	0.00		32	
	non noble metal	lead	7439-92-1	2.240	0.15	0.15	1532	1604
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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